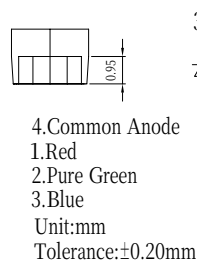
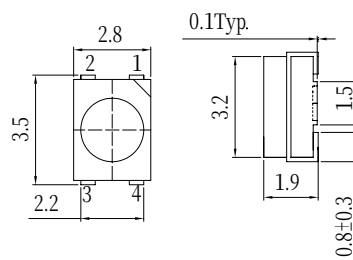


■Features

- High Luminous PLCC4 Top SMD LEDs
- 3.5x2.8x1.9mm Standard Directivity
- Superior Weather-resistance
- UV Resistant Silicone
- White Diffused Type

■Outline Dimension



■Applications

- Toys
- Audio
- Games
- Other Lighting

■Absolute Maximum Rating (Ta=25°C)

Item	Symbol	Value		Unit
		Red	G/B	
DC Forward Current	I_F	30	30	mA
Pulse Forward Current*	I_{FP}	100	100	mA
Reverse Voltage	V_R	5	5	V
Power Dissipation	P_D	78	108	mW
Operating Temperature	T_{opr}	-30 ~ +85		°C
Storage Temperature	T_{stg}	-40 ~ +100		°C
Lead Soldering Temperature	T_{sol}	260°C/5sec		-

*Pulse width Max.10ms Duty ratio max 1/10

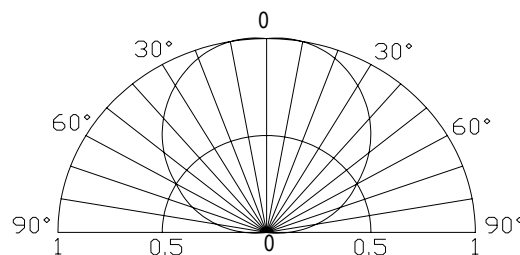
■Electrical -Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
DC Forward Voltage	V_F (Red)	$I_F=20mA$	1.8	2.1	2.6	V
	V_F (G/B)	$I_F=20mA$	2.9	3.1	3.6	V
Reverse Current	I_R	$V_R=5V$	-	-	10	μA
Domi. Wavelength*	λ_D (Red)	$I_F=20mA$	620	625	630	nm
	λ_D (Green)	$I_F=20mA$	520	525	530	nm
	λ_D (Blue)	$I_F=20mA$	465	470	475	nm
Luminous Intensity*	I_v (Red)	$I_F=20mA$	330	500	-	mcd
	I_v (Green)	$I_F=20mA$	330	450	-	mcd
	I_v (Blue)	$I_F=20mA$	150	200	-	mcd
50% Power Angle	$2\theta_{1/2}$	$I_F=20mA$	-	120	-	deg

*1 Tolerance of dominant wavelength is ±1nm

*2 Tolerance of luminous intensity is ±15%

■Directivity



Soldering Heat Reliability (DIP):

IR Reflow soldering Profile

- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.
- Repairing should not be done after the LEDs have been soldered.

When repairing is unavoidable,

a double-head soldering iron should be used.

It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

